



Single-Chip Facsimile Controller

Preliminary

Overview

The LC82151 is a facsimile controller that integrates the main functions required by facsimile systems on a single chip. The LC82151 includes a FAX modem with ADPCM and HDLC functions, image processing functions that can create high-quality binary image data without external memory, a CODEC accelerator, a CPU and CPU peripheral circuits, general-purpose I/O ports, and other functions. A facsimile system with excellent cost-performance characteristics can be created easily by providing ROM and RAM.

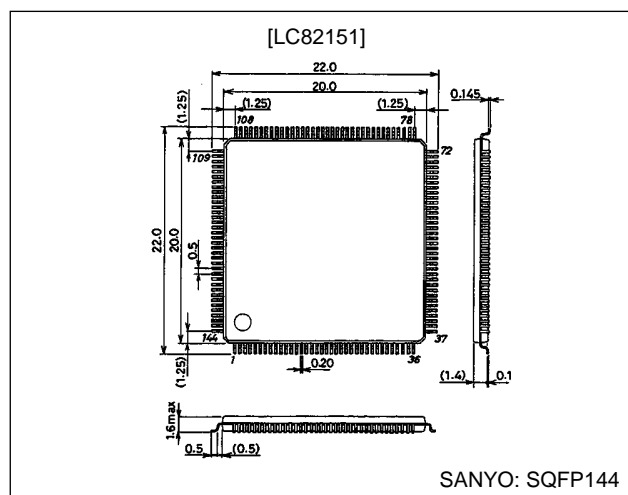
Functions

- CPU and peripheral circuits
 - High-speed 16-bit CPU (65C816) operating at 7.4 MHz
 - 16-MB program address space
 - CODEC accelerator
 - Two-channel DMA controller
 - Four 16-bit timers
 - 16-bit watchdog timer
 - TPH interface
 - Serial I/O interface
 - Parallel I/O: 10 to 43 pins
- Image processing
 - Processes 2048 pixels per line
 - Processing speed: 540 ns per pixel (maximum)
 - Built-in 8-bit A/D converter (Includes a sensor signal delay function.)
 - Sensor drive circuit (Supports CCDs and all major CIS devices.)
 - Distortion correction (White distortion: 8-pixel averaging correction, black correction: Allows the black correction subtraction data to be set.)
 - γ -correction (Supports user-defined correction curves.)
 - Simple binary conversion processing (fixed threshold and density-adaptive threshold)
 - Halftone processing error diffusion method (64 levels)
 - Image reduction (decimation, fine black line retention, and fine white line retention)
- Modem
 - Group 3 FAX modem
 - ITU-T V.29 (9600, 7200, and 4800 bps)
 - ITU-T V.27ter (4800 and 2400 bps)
 - ITU-T V.21ch2 (300 bps)
 - Simultaneous high/low-speed wait function
 - Short training function (ITU-T V.27ter only)
 - HDLC function (for all transmission speeds)
 - Synthesizer function
 - Caller ID function
 - Bell 202 (1200 bps)
 - ITU-T V.23 (1200 bps)
 - ADPCM function
 - Encoding: 2, 3, or 4 bits
 - Sampling frequencies: 9.6, 7.2, 4.8, and 3.6 kHz
 - RTC low-voltage backup
 - 5-V single-voltage power supply

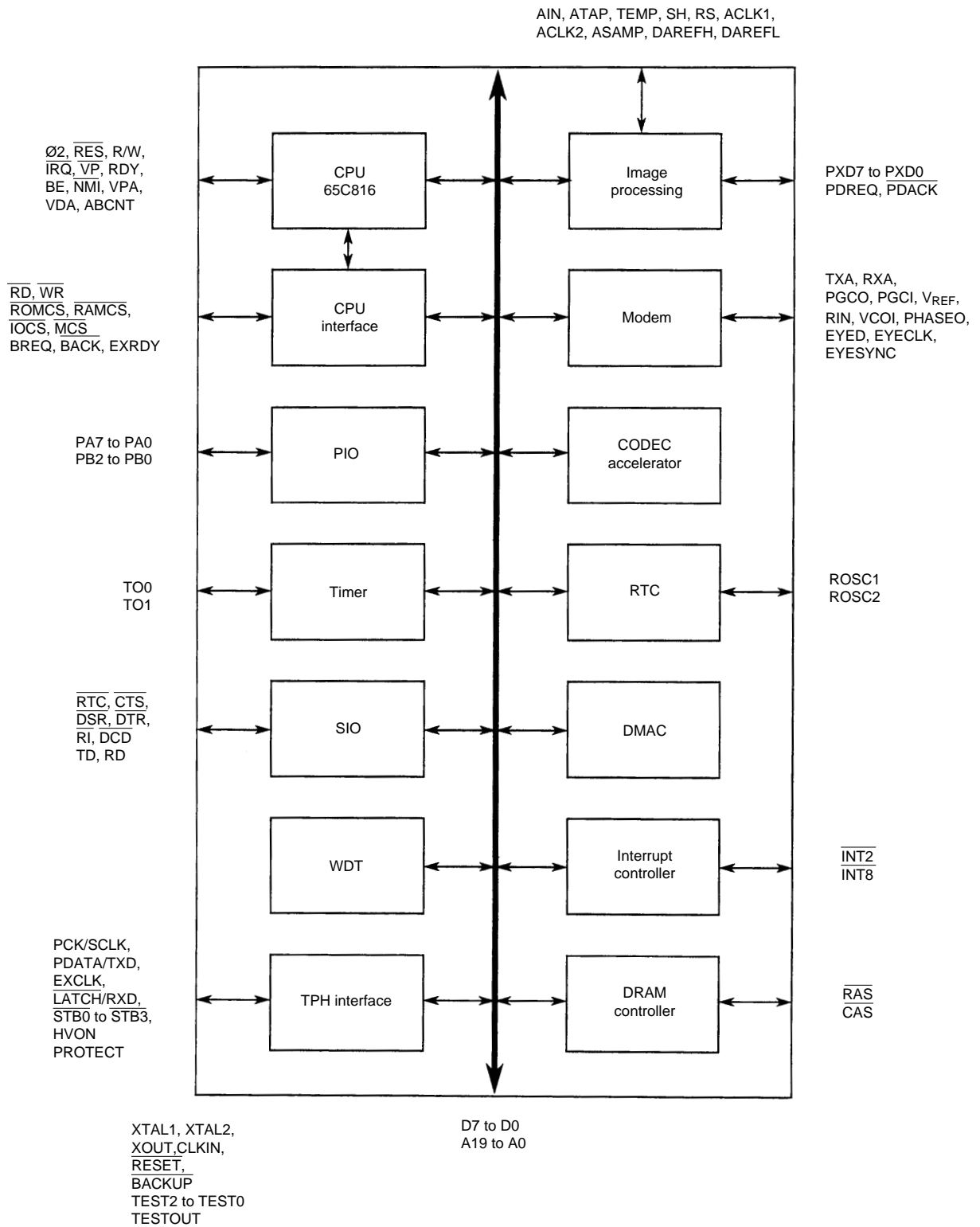
Package Dimension

unit: mm

3214-SQFP144



Block Diagram



Pin Assignment

Type					
I	Input pins	B	Bidirectional pins	NC	No connection
O	Output pins	P	Power pins		

Pin No.	Pin	I/O	Pin function
1	V _{SS}	P	Ground
2	\overline{VP}	I	ICE vector address signal
3	RDY	O	ICE ready signal
4	VPA	I	ICE valid program address signal
5	VDA	I	ICE valid data address signal
6	A19	O	Address bus
7	A18	O	
8	A17	O	
9	A16	O	
10	D7	B	Data bus
11	D6	B	
12	D5	B	
13	D4	B	
14	D3	B	
15	D2	B	
16	D1	B	
17	D0	B	
18	V _{DD}	P	Power supply
19	V _{SS}	P	Ground
20	\overline{RD}	O	Read signal from the CPU
21	\overline{WR}	O	Write signal from the CPU
22	\overline{ROMCS}	O	Program ROM chip select signal
23	\overline{RAMCS}	O	Working RAM chip select signal
24	\overline{IOCS}	O	External I/O chip select signal
25	\overline{MCS}	O	External I/O chip select signal
26	$\overline{RAS}/PG1$	B	DRAM row address strobe/general-purpose port G
27	$\overline{CAS}/PG2$	B	DRAM column address strobe/general-purpose port G
28	PA7	B	General-purpose port A
29	PA6	B	
30	PA5	B	
31	PA4	B	
32	PA3	B	
33	PA2	B	
34	PA1	B	
35	PA0	B	
36	V _{SS}	P	Ground
37	V _{DD}	P	Power supply
38	RIN	I	PLL bias input
39	PHASEO	O	PLL phase detector output
40	VCOI	I	PLL voltage-controlled oscillator input
41	$\overline{INT8}/PB7$	B	External interrupt request signal/general-purpose port B
42	$\overline{INT2}/PB6$	B	
43	$\overline{BACK}/PB5$	B	CPU bus acknowledge signal/general-purpose port B
44	BREQ/PB4	B	CPU bus request signal/general-purpose port B
45	EXRDY/PB3	B	External ready input/general-purpose port B
46	PB2	B	General-purpose port B
47	PB1	B	
48	PB0	B	
49	\overline{NMI}	I	Non-maskable interrupt request signal
50	TEST2	I	Test pin

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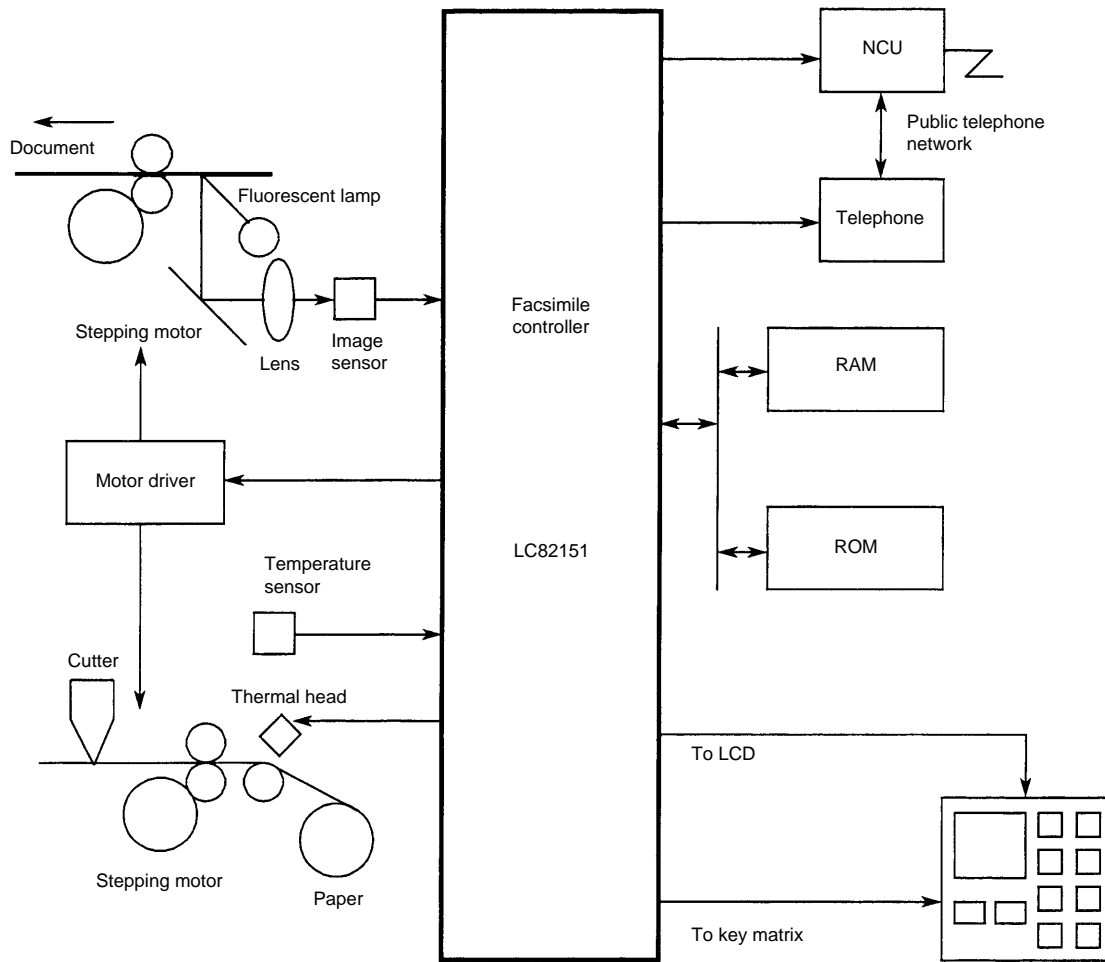
Pin No.	Pin	I/O	Pin function
51	TEST1	I	Test pins
52	TEST0	I	
53	TESTOUT	I	
54	V _{DD}	P	Power supply
55	V _{SS}	P	Ground
56	ROSC1	I	RTC crystal oscillator connections
57	ROSC2	O	
58	BACKUP	I	Low power mode input
59	RESET	I	System reset signal
60	AV _{DD}	P	Analog system power supply
61	AV _{SS}	P	Analog system ground
62	AIN	I	Sensor signal input
63	TEMP	I	Thermistor input
64	ATAP	O	A/D converter reference voltage output
65	DAREFH	I	D/A converter high-level reference voltage input
66	DAREFL	I	D/A converter low-level reference voltage input
67	TXA	O	Modem analog transmit output
68	RXA	I	Modem analog receive input
69	PGCO	O	Modem gain adjustment output
70	PGCI	I	Modem gain adjustment input
71	V _{REF}	I	Modem analog block reference input
72	V _{SS}	P	Ground
73	V _{DD}	P	Power supply
74	SH	O	Image sensor start pulse
75	RS	O	Image sensor reset pulse
76	ACLK1	O	Image sensor data transfer clocks
77	ACLK2	O	
78	ASAMP	O	Built-in A/D converter sampling point monitor signal
79	PXD7/PC7	B	Image data output/general-purpose port C
80	PXD6/PC6	B	
81	PXD5/PC5	B	
82	PXD4/PC4	B	
83	PXD3/PC3	B	
84	PXD2/PC2	B	
85	PXD1/PC1	B	
86	PXD0/PC0	B	
87	PDREQ/PF7	B	Image data DMA request signal/general-purpose port F
88	PDACK/PF6	B	Image data DMA acknowledge signal/general-purpose port F
89	EYED/PF5	B	Eye pattern data output/general-purpose port F
90	V _{DD}	P	Power supply
91	V _{SS}	P	Ground
92	EYECLK/PF4	B	Eye pattern data clock/general-purpose port F
93	EYESYNC/PF3	B	Eye pattern data synchronizing signal/general-purpose port F
94	TO1/PF2	B	Timer outputs/general-purpose port F
95	TO0/PF1	B	
96	PCK/SCLK/PE7	B	Thermal head data transfer clock/serial I/O clock/general-purpose port E
97	PDATA/TXD/PE6	B	Thermal head serial output data/serial I/O send data/general-purpose port E
98	EXCLK/PE5	B	Thermal head control external clock/general-purpose port E
99	LATCH/RXD/PE4	B	Thermal head data latch signal/serial I/O receive data/general-purpose port E
100	STB3/PE3	B	Thermal head strobe signal/general-purpose port E
101	STB2/PE2	B	
102	STB1/PE1	B	
103	STB0/PE0	B	
104	HVON/PF0	B	Head power on/off control signal/general-purpose port F
105	PROTECT/PG0	B	Head protection abnormality indication signal input/general-purpose port G

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Pin No.	Pin	I/O	Pin function
106	XTAL1	I	System clock crystal oscillator element connection (29.4912 MHz)
107	XTAL2	O	
108	V _{SS}	P	Ground
109	V _{DD}	P	Power supply
110	XOUT	O	Crystal oscillator clock output
111	CLKIN	I	System clock input
112	A15	B	Address bus
113	A14	B	
114	A13	B	
115	A12	B	
116	A11	B	
117	A10	B	
118	A9	B	
119	A8	B	
120	TD/PD7	B	Serial port transmit data output/general-purpose port D
121	RD/PD6	B	Serial port receive data input/general-purpose port D
122	$\overline{\text{RTS}}$ /PD5	B	Request to send signal/general-purpose port D
123	$\overline{\text{CTS}}$ /PD4	B	Clear to send signal/general-purpose port D
124	$\overline{\text{DSR}}$ /PD3	B	Data set ready/general-purpose port D
125	$\overline{\text{DTR}}$ /PD2	B	Data terminal ready/general-purpose port D
126	V _{DD}	P	Power supply
127	V _{SS}	P	Ground
128	$\overline{\text{RI}}$ /PD1	B	Ring indicator/general-purpose port D
129	$\overline{\text{DCD}}$ /PD0	B	Data carrier detect/general-purpose port D
130	A7	B	Address bus
131	A6	B	
132	A5	B	
133	A4	B	
134	A3	B	
135	A2	B	
136	A1	B	
137	A0	B	
138	ABCNT	O	ICE bus control signal
139	BE	O	ICE bus enable signal
140	$\phi 2$	O	ICE system clock
141	$\overline{\text{RES}}$	O	ICE reset signal
142	RWB	I	ICE read/write signal
143	$\overline{\text{IRQ}}$	O	ICE interrupt request signal
144	V _{DD}	P	Power supply

Sample Application



Specifications

Absolute Maximum Ratings at $T_a = 25^\circ\text{C}$, $V_{SS} = 0\text{ V}$

Parameter	Symbol	Conditions	Ratings	Unit
Maximum supply voltage	$V_{DD\text{ max}}$		-0.3 to +7.0	V
Input and output voltage	V_i, V_o		-0.3 to $V_{DD} + 0.3$	V
Allowable power dissipation	$P_d\text{ max}$	$T_a = 70^\circ\text{C}$	550	mW
Operating temperature	T_{opr}		-30 to +70	$^\circ\text{C}$
Storage temperature	T_{stg}		-55 to +125	$^\circ\text{C}$
Soldering temperature		Manual soldering (3 seconds)	350	$^\circ\text{C}$
		Reflow soldering (10 seconds)	235	$^\circ\text{C}$

Allowable Operating Ranges at $T_a = -30\text{ to }+70^\circ\text{C}$, $V_{SS} = 0\text{ V}$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Supply voltage	V_{DD}		4.5		5.5	V
Input voltage	V_{IN}		0		V_{DD}	V

Electrical Characteristics at $T_a = -30\text{ to }+70^\circ\text{C}$, $V_{DD} = 4.5\text{ to }5.5\text{ V}$

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Input high-level voltage	V_{IH1}		2.2			V
Input low-level voltage	V_{IL1}				0.8	V
Input leakage current	I_L		-10		+10	μA
Output high-level voltage	V_{OH}	$I_{OH} = -4\text{mA}$	2.4			V
Output low-level voltage	V_{OL}	$I_{OL} = 4\text{mA}$			0.4	V
Output leakage current	I_{OZ}	When outputs are high impedance	-10		+10	μA
Charge pump output current	I_{POZ}	PHASE0 = 2 V	7	15	27	mA
	I_{NOZ}	PHASE0 = 2 V	-8	-15	-28	mA
Vref input voltage	V_{REF}	V_{REF}		$V_{DD}/2$		V
Vref impedance	V_{REF}	V_{REF}	1			M
Input voltage range	V_{IA}	RXA, PGCI	$V_{DD} \times 0.2$		$V_{DD} \times 0.8$	V
Operating voltage range	V_{OA}	TXA, PGCO	$V_{DD} \times 0.2$		$V_{DD} \times 0.8$	V
Output impedance	R_O	TXA, PGCO			7.0	k
Oscillator frequency	f_{CLK1}	XTAL1, XTAL2, CLKIN		29.4912		MHz
	f_{CLK2}	ROSC1, ROSC 2		32.768		kHz
Current drain	I_{DD1}	Operating		100		mA
	I_{DD2}	In backup mode, $V_{DD} = 2.5\text{ V}$, $\overline{\text{BACKUP}} = 0$		5		μA

Power on Timing

Applications must control the timing of the power on sequence carefully. Although AV_{SS} and V_{SS} are completely isolated internally in the LC82151, AV_{DD} and V_{DD} are connected through the substrate. This means that there must be no potential difference between AV_{DD} and V_{DD} . Also, the power supply voltage rise and fall times must be under 3 ms.

Analog Characteristic

D/A Converter

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Resolution				6		bit
Reference resistors value		DAREFL, DAREFH		5.0		k

A/D Converter at an ATAP potential of 4.2 V

A/D Converter

Parameter	Symbol	Conditions	Ratings			Unit
			min	typ	max	
Resolution				8		bit
Linearity error					± 1	LSB
Differential linearity error					± 1	LSB

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